

The IBE-215 is designed for inert gas ion beam etching as well as for reactive ion beam etching. He-backside cooling, SIMS for end point detection, interface for clean room, beam monitoring with Faraday cup array and other helpful features are available.



## TECHNICAL DATA

### WORK PIECE DATA

Size:	Ø215 mm – 152.4 mm x 152.4mm (Ø8.5" – 6" x 6")
Thickness:	20 mm (0.8")
Weight:	max. 2 kg (4.4 lbs)
Contact angle:	0 – 90°
Rotation speed:	0 – 10 rpm
Shape:	plane, spherical, aspherical, freeform

### SINGLE LOAD LOCK SYSTEM

Loading time:	< 2min.
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### AXIS SYSTEM

Type: 215	X, Y, A, B
Travel:	X > 500 mm Y = 300 mm A ± 95° B = 360°

### DIMENSIONS

Weight:	2000 kg (4400 lbs)
WxHxD:	2.8 m x 2.4 m x 1.4 m (110" x 94" x 55")
Footprint:	4 m x 2 m (157" x 79")

# (R)-IBE215

